

ABSTRACT OF THE DISCLOSURE

It is an object of the present invention is to provide a method for manufacturing a multi-layered ceramic electronic component which can 5 reliably prevent a multi-layered unit including a ceramic green sheet and an electrode layer from being damaged and efficiently laminate a desired number of the multi-layered units, thereby manufacturing the multi-layered ceramic electronic component.

The method for manufacturing a multi-layered ceramic electronic 10 component according to the present invention includes a step of positioning a multi-layered unit including a release layer, an electrode layer and a ceramic green sheet formed on a support sheet in such a manner that the surface of the multi-layered unit is located on a base substrate and a step of pressing the multi-layered unit toward the base 15 substrate, thereby laminating the multi-layered unit on the base substrate, and employs as the base substrate a base substrate having such surface roughness as to include per 0.01 mm^2 thereof not more than one protrusion that can penetrate the ceramic green sheet of the multi-layered unit laminated on the base substrate to half or more the thickness 20 of the ceramic green sheet and include per 100 mm^2 thereof not more than one protrusion that can completely penetrate the ceramic green sheet.